Evolution of Chip Supply Chain Traceability

Global Ecosystem Business Collaboration for Hyperconnected Planet from End Applications to Semiconductor Provenance

Tom Katsioulas
President & CEO
Archon Design Solutions
tomkat@archon-ds.com

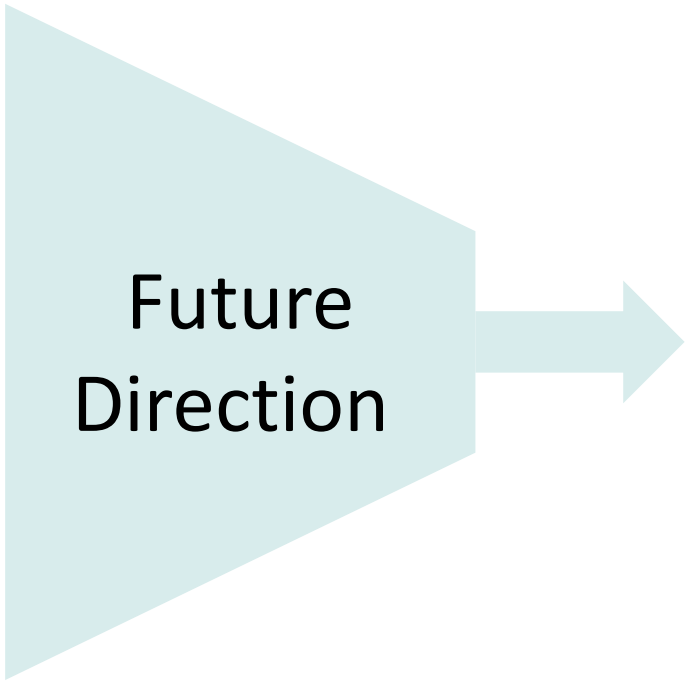
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Evolution – From Chip Security to Ecosystem Alliance

- **Security at Mentor and Siemens 2016-2020**
  - Secure Silicon Supply Chain Prototype (Shift Right)
  - Secure Device Onboarding and Charter of Trust (Shift Left)

- **GSA TIES to IoT Advisory Board (2020-2023)**
  - Operationalizing Collaborative Business Ecosystem
  - Digitalization paper leads to IoT Advisory Board

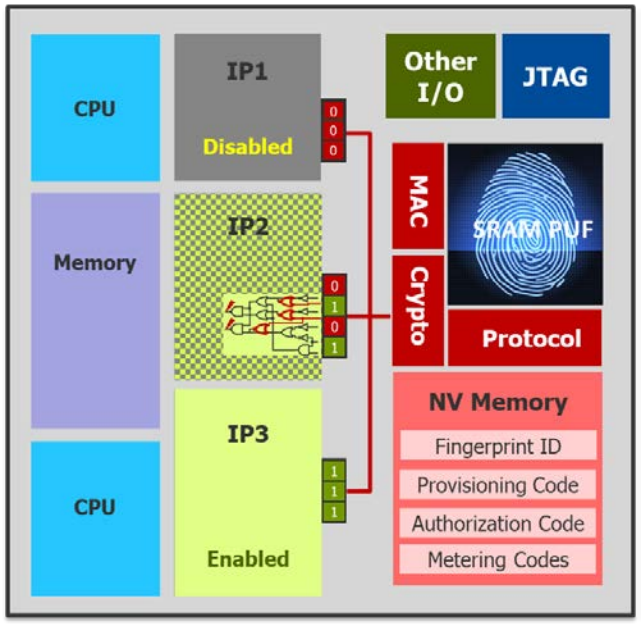
- **IoTAB, Foundry-CA and STAMP Initiative (2023-2025)**
  - Progress in IoTAB → CA based Solution for Traceability
  - STAMP Coalition, EU-US Workshops, SEMI support

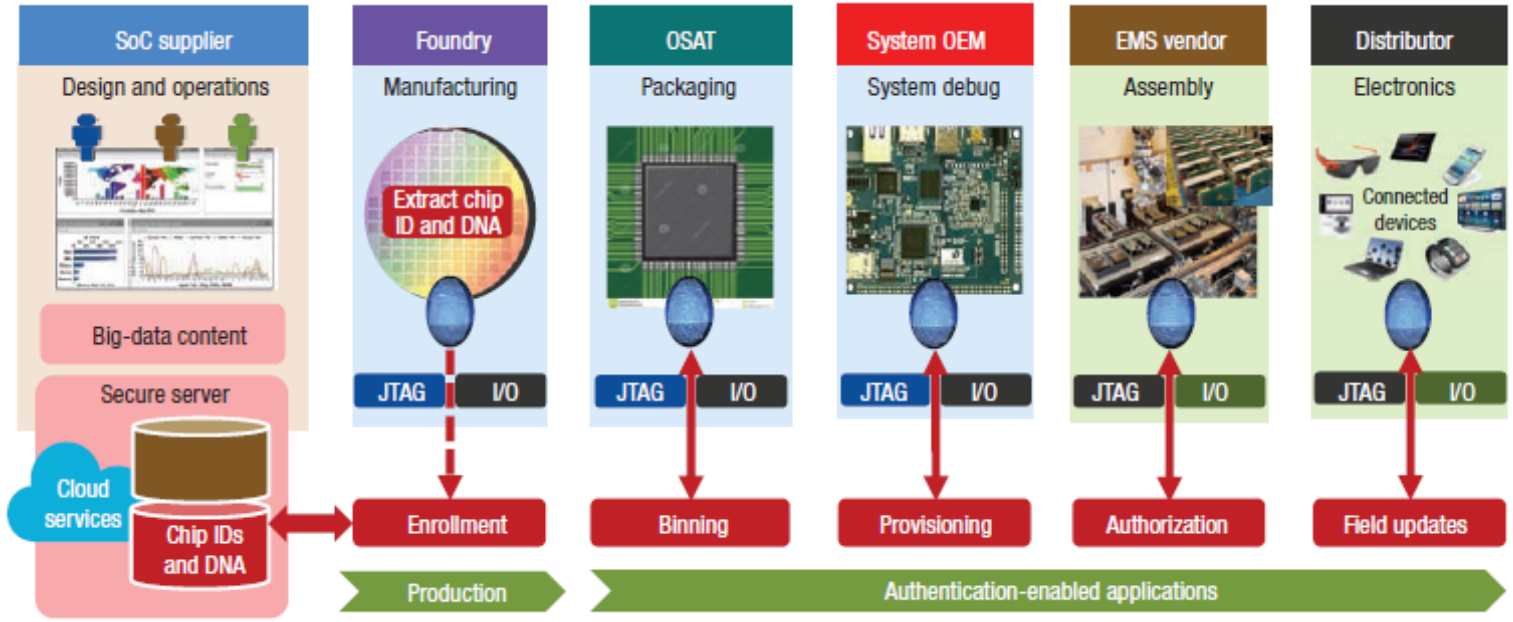


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2016 - Secure Supply Chain Platform (Shift Right)

Computer Magazine - A Platform Solution for Secure Supply-Chain and Chip Life-Cycle Management

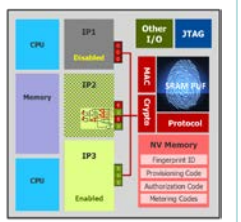




Security + Fingerprint → Enrollment 1st Power Up → Supply Chain Security

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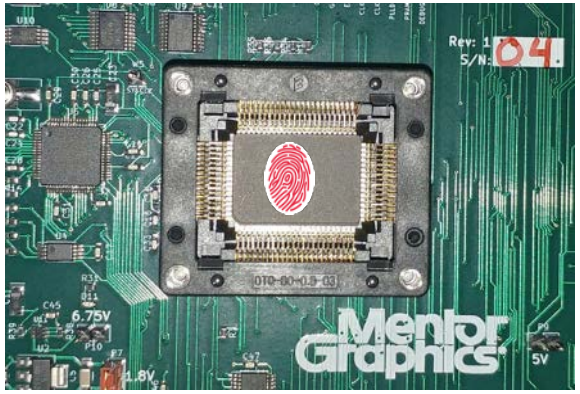
2017-2018 - Secure Silicon Link to Systems (Shift Right)



Mentor®
A Siemens Business



tsmc





semi

T23 Standard

intel

SIEMENS

Infineon





SIEMENS



IPC427



Azure MindSphere

fido™ ALLIANCE

FDO Standard

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2019 Trusted Traceability Vision (Shift Left)

*Developed at Siemens

Charter of Trust

P2 Security in Supply Chain

P3 Security by Default

P6 Education Internal - External

P7 Certification of Infrastructure

P10 Joint Initiatives

End Users

Trusted Applications

Chip Suppliers

4 Root of Trust

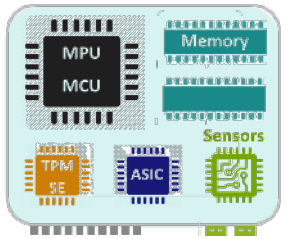
3 Certificates

2 Provisioning

1 Onboarding

Trusted Digital Twins









Distributors

Trusted Traceability

semi IPC TRUSTED COMPUTING GROUP fido ALLIANCE

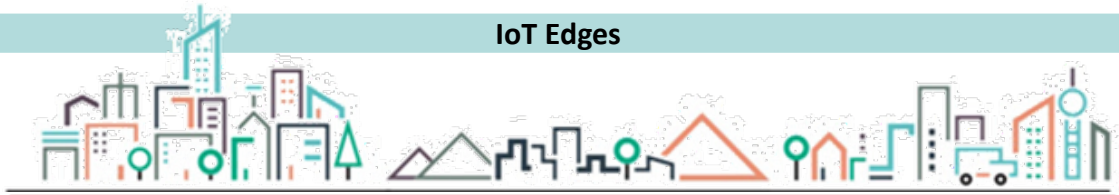
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*Blockchain and Open API Standards to attract suppliers & partners

2020 - Smart Connected Supplier Economics

Industrial | Manufacturing | Aerospace | Defense | Mobility | Communications | Computing | Healthcare

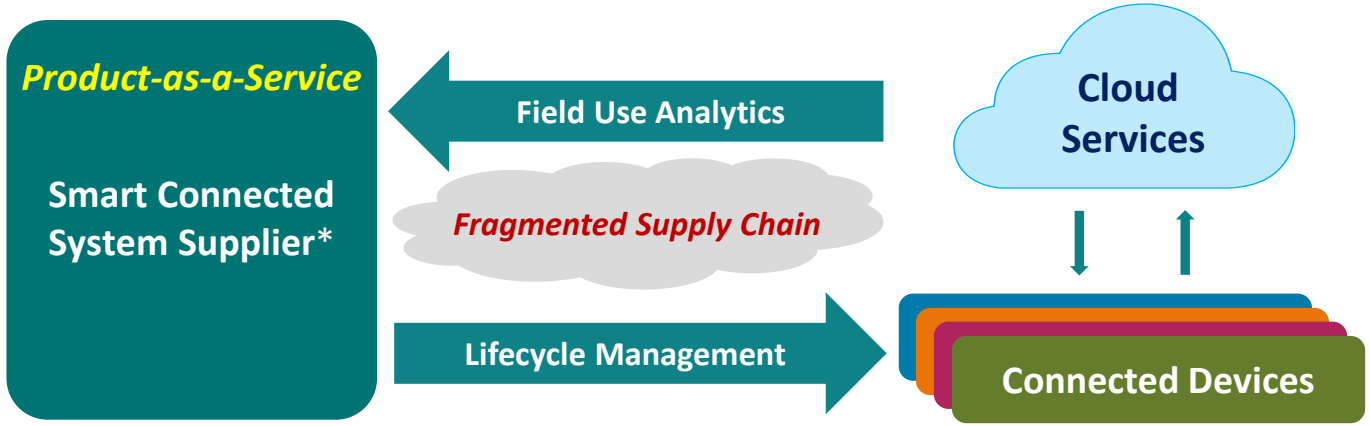
OT Edges — IoT Edges — IT Edges



Billions of Connected Devices

Powered by trillions of chips

Smart industries, Cities and Transportation Infrastructure



- Better visibility on product field use
- Remote lifecycle management
- Reduced support costs and RMAs
- Lower OPEX, higher differentiation
- Add-on XaaS* revenue Streams
- **Security, Trust and Data Sharing**

*Sources: HBR, HPE

*XaaS: Everything-as-a-Service

How to develop strategy based on trusted data to drive value and economic growth?

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2020 - TIES™ Supply Chain Collaboration Platform

Semiwiki - Trusted IoT Ecosystem for Security – Created by the GSA and Chaired by Mentor/Siemens

GSA - ~260 members in 2020



Semiconductors *EDA, IP, IC, Foundries, OSATs*

Devices & Systems *ODMs, Systems, OEMs, EMS*

IoT Applications *CSPs, IT, PLM, Apps, Operators*

- **Objective:** Promote secure IoT services for end users
- **Benefits:** Drive member retention and engagement
- **Value:** Grow membership with end-to-end solutions
- **Openness:** Members to add value in an open way
- **Interactions:** Multiply value with network effects
- **Governance:** Grow Ecosystem IQ across value chain

50+ companies and 150+ contributors in 2 years

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2021 - Business Ecosystem Principles

Platform = Open participation with **rules of governance**, designed to **maximize interactions**



Orchestration
Add-Value in a Uniform Way

- Use Case Driven
- Solutions Focus
- Economic Value*

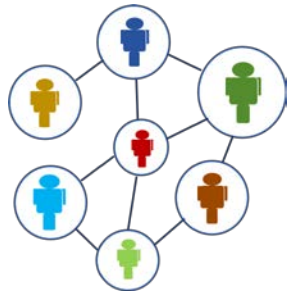
*For Participating Stakeholders



Governance
Steer Community Behavior

- JSA* Compliance
- Group Leadership
- Team Processes

*Joint Stakeholder Agreement



Network Effects
Leverage Ecosystem IQ

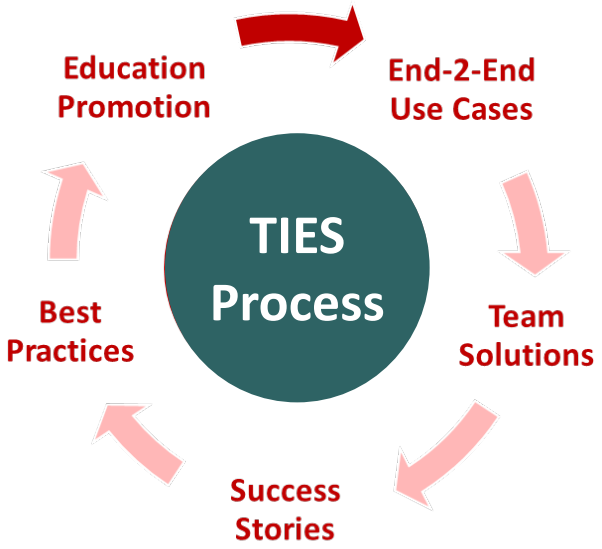
- Knowledge Share
- Chained Collaboration*
- Foster Partnerships

*Drives Membership Growth

*Source: https://sloanreview.mit.edu/article/platform-strategy-and-the-internet-of-things/

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2021 - TIES Operating Model, Forms and Guides



Content Categories
Hardware Design Security
Trusted Supply Chain
Vulnerability & Trust Metrics
Embedded System Security
Security Infrastructure
Edge, ML, AIoT Applications
Trusted Digital Twins
New XaaS Business Models

Content Type
Solutions White Papers
Presentations
Webinars
PoC Demonstrators
Security Newsletters
Standards Taxonomies
Best Practices Guides
Liaison ORG Synergies

Elevator Brief
Executive Summary
Industry Problem
Use Case Examples
Proposed Solution
Beneficiaries
Value Proposition
Industry Guidelines
Partnerships outside of ORG

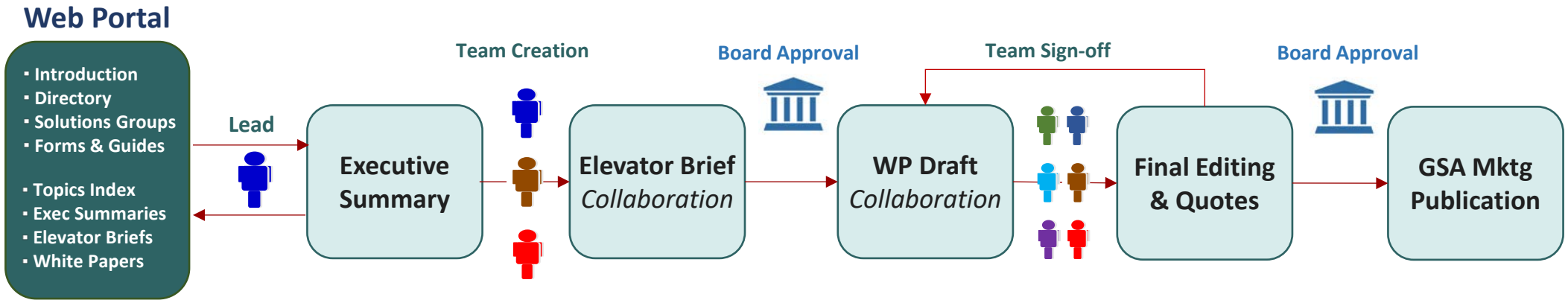
- **Use Cases:** Identify challenges in the IoT value chain by vertical market or application
- **Solutions:** Describe end-to-end solutions carried out by collaborating stakeholders
- **Economics:** Articulate clear benefits and value proposition for shared monetization
  - *Accelerate adoption, reduce OPEX/Cost/Risk, increase product value, enable new revenue streams, etc.*

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2022 - TIES Multi-Stakeholder Operating Process

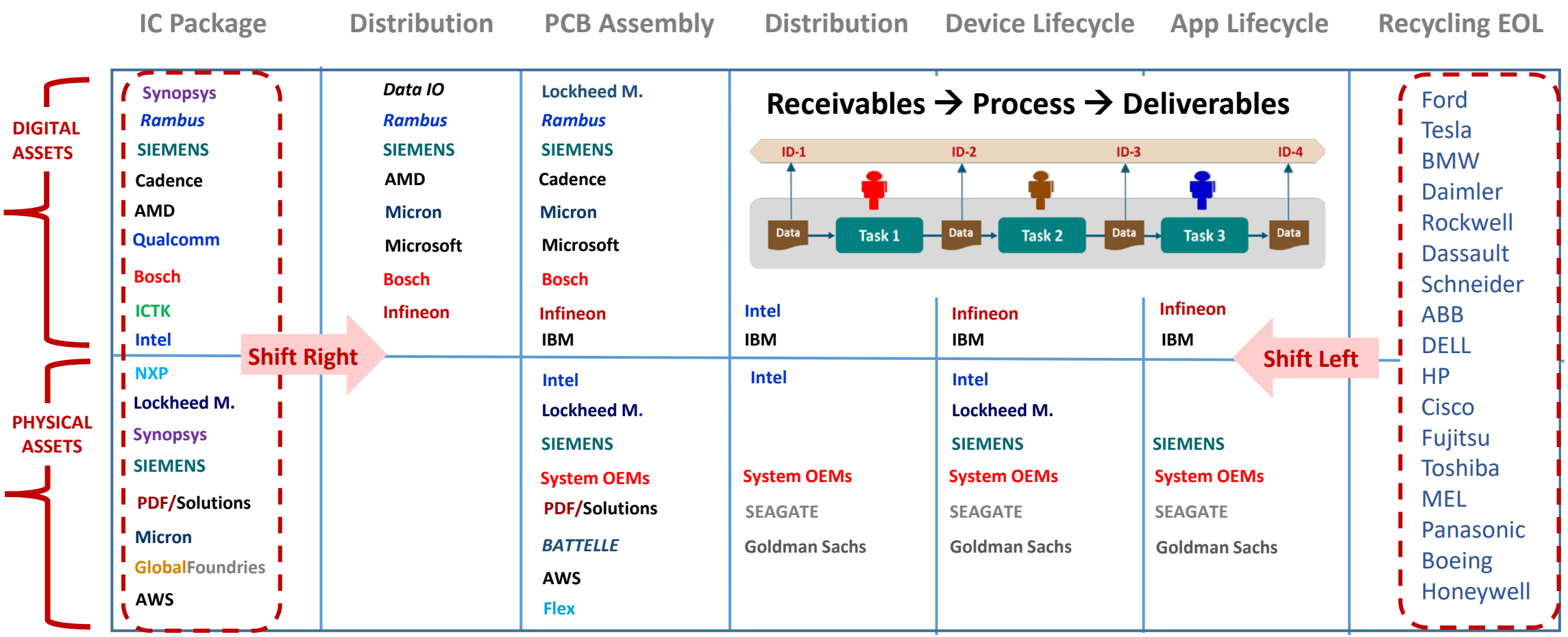
Multiple teams working in parallel on different slices of Supply Chain



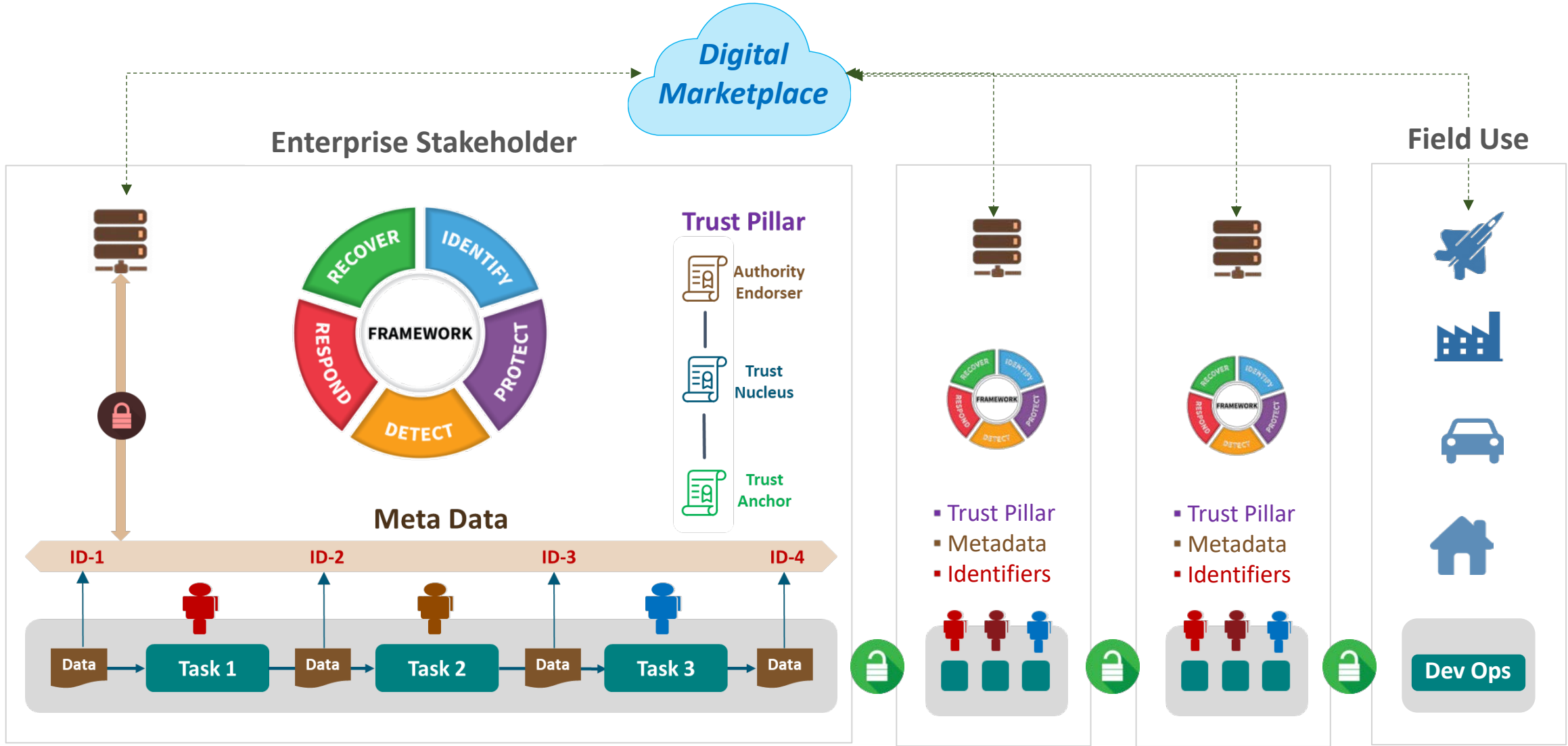
- **SWG Orchestration -** Leads post an Executive Summary for a solution use case
- **Team Creation -** Diverse expertise develop business case Elevator Pitch & Brief
- **Collaboration** - Contributors recruit more experts from their networks to fill gaps
- **Board Approval** - Once a white paper if done team signs-off for Board for approval
- **Joint Promotion** - ORG promotes white paper with all logos and shared copyright

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2022 - Digitalizing the Supply Chain ‘Piecemeal’



2022 - TIES Digitalization Vision Published by NIST

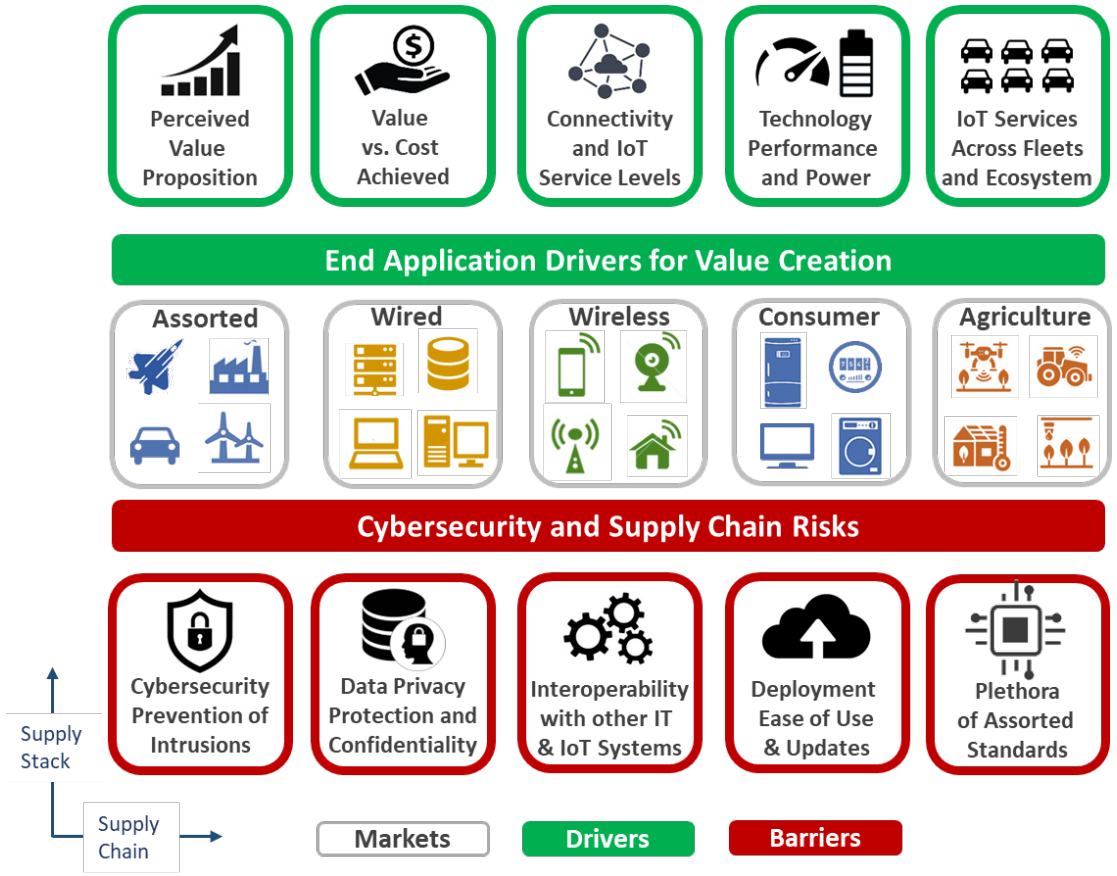


*Source: [GSA TIES reply to NIST RFI on Cybersecurity Framework and Supply Chain Risk Management]

2023 - IoTAB Raise Awareness for Ecosystem Vision

U.S. Department of Commerce Appoints Members for New Internet of Things Advisory Board

- **Convergence of digital and physical world drives new digital economies by 2030***
- **Global GDP $5.5 to $12.6T value, IoT, AI, Cloud, Quantum fueled by 41B+ devices, 800+ ZB data**
- **Supply chain disaggregation, dark distribution channels, silos, threaten critical infrastructure**
- **No single company can sway supply chains, this is a mandate for ecosystem collaboration**



*Sources: McKinsey & Company (IoT), GlobalDots, ABI Research, Semiconductor Digest, McKinsey & Co (Security))

2023 - IoTAB Markets Fueled by Chips Value Chains

IoT Markets $Billion	2021	2030	CAGR %	Top Chip Suppliers *Supply Chain Provenance*	Top System OEMs *Enterprise-level Traceability*	IoT Devices & Systems *Supply Chain Traceability*	End Applications (Edge) *Smart City & Critical Infrastructure*
Industrial	**326.1**	**1742.8**	**20.5%**	TI, Infineon, ADI, ST, Renesas, NXP, Maxim, Microchip, ON Semi, Micron, GF, TSMC	IBM, Siemens, Cisco, GE, Schneider, Rockwell, PTC, Microsoft, SAP, Honeywell	DCS, PLCs, SCADA, UPS, Systems (Remote Monitoring, Control , Intrusion Detection)	Manufacturing, Energy & Power, Oil & Gas, Smart & Critical Infrastructure, Logistics & Transport, Agriculture
Manufacturing	**205.8**	**1523.9**	**24.9%**	Intel, Advantech, Kontron, NXP, TI, Infineon, ADI, ST, NVIDIA, Renesas, GF, TSMC	Siemens, ABB, Honeywell, Emerson, Schneider, MEL, GE, Rockwell, Bosch	PLCs, HMIs, IPCs, I/O modules, Sensors, SCADA, RFID, Drives, Power, Process/Motion Auto	PROCESS: Energy, Utilities, Chemical, Food & Bev, Water/Waste; DISCRETE - Automotive, Machine, Electronics
Automotive	**82.7**	**621.8**	**25.1%**	NXP, Infineon, TI, ST, Renesas, ADI, ON Semi, Qualcomm, Intel, Micron, GF, TSMC	Toyota, VW, Hundai, GM, Ford, Honda, Nissan, BMW, Daimler, KIA, Audi, Tesla	ECUs, CAMs, ABS, ADAS, ECM, ACC, TPMS, ESC, Navigation, Infotainment, Telematics	Fleet Management, V2V Comms, Vehicle to infrastructure, Autonomy, Telematics, Navigation, Infotainment
Consumer	**221.7**	**616.7**	**12.0%**	Qualcomm, MediaTek, NXP, TI, Broadcom, Samsung, Intel, ST, Infineon, Micron, TSMC	Amazon, Google, Samsung, LG, Xiaomi, Philips, Nest , Bosch, Whirlpool, Electrolux	Smart Home - thermostats, locks, lighting, appliances, motion sensors, irrigation	Wired, Wireless Connectivity; Consumer Electronics, Healthcare, Wearables, Automotive Gadgets
Transportation	**85.2**	**498.5**	**21.7%**	NXP, Infineon, TI, ST, Renesas, ADI, ON Semi, Micron, Maxim, Intel, GF, TSMC	Bosch, Continental, Denso, Magna, Valeo, Aptiv, ABB, Siemens, Cisco, Schneider	Automotive, GPS, Control Systems, Diagnostics, ITS, Traffic, Collision Avoidance	Road/Rail/Airways, Maritime; Traffic Control, Telematics, Security and Surveillance , Remote Monitoring
A&D	**42.4**	**156.3**	**15.6%**	Intel, ADI, Xilinx, TI, ST, NXP, Infineon, Microchip, ON Semi, GF, Maxim, Micron, TSMC	Boeing, Airbus, Lockheed Martin, Northrop Grumman, Raytheon, BAE Systems, etc.	Systems - Radar, Sonar, Flight Control, Avionics, Missile guidance, Satellites	Fleet Management, Equipment Maintenance, Security, Space Systems, Air/Sea/Ground Vehicles

Provenance Is Here

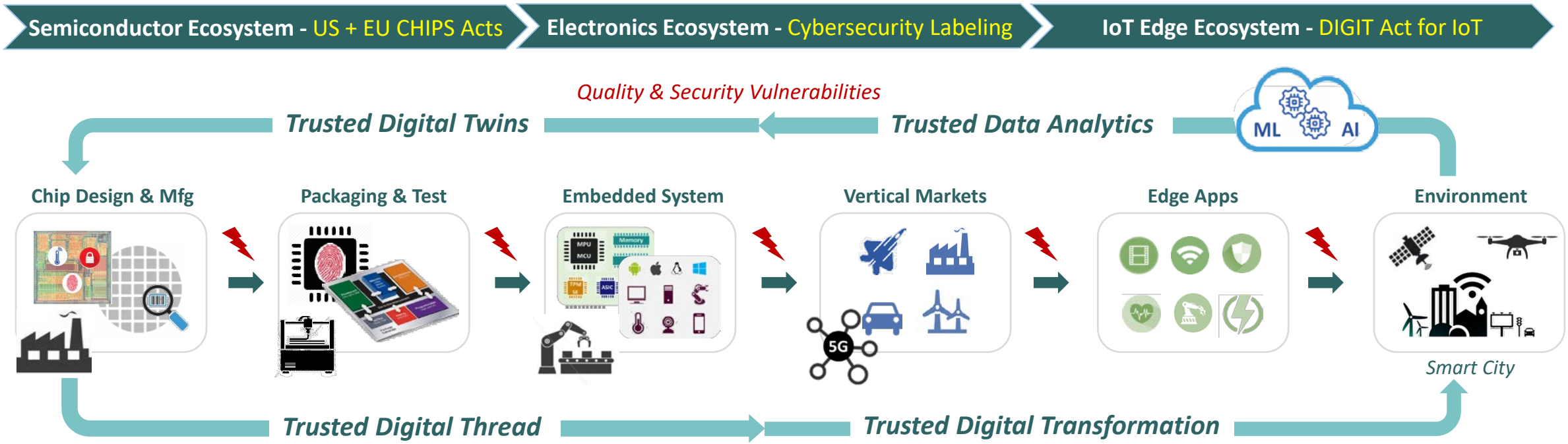
*Source: https://www.precedenceresearch.com/

Monetization is Here

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2023 - IoTAB Orchestrating Chip-based Value Chain

*Electronics & Semiconductors



Trusted Business Ecosystems

- **Semis** – IP, EDA, IC Foundry, OSAT
- **Systems** – PCB, EMS, ODM, OEM
- **Edge Apps** – CSP, IT, PLM, Edge Apps

Connected Value Creation

- **Traceability** - Establish Market Preference
- **Digital Thread** - Enable Data Marketplaces
- **Monetization -** Drive New Revenue Streams*

*XaaS and Data-driven AI/ML Applications

2023 - IoTAB Promoting US-EU Collaboration

U.S. Cyber Trust Mark

Consumer → Industrial IoT



Security & Privacy Overview

Smart Device Co.

Smart Video Doorbell NS200
Firmware version: 2.5.1 - updated on: 11/12/2020
The device was manufactured in: China

Security Mechanisms

Security updates	Automatic - Available until at least 1/1/2022
Access control	Password - Factory default - User changeable, Multi-factor authentication, Multiple user accounts are allowed

Data Practices

	Visual	Audio	Physiological	Location
Sensor data collection				
Sensor type	Camera	Microphone		
Purpose	Providing device functions	Providing device functions, Research		
Data stored on device	Identified	No device storage		
Data stored on cloud	Identified	Identified - Option to delete		
Shared with	Manufacturer, Government	Manufacturer		
Sold to	Not disclosed	Not sold		

Other collected data: Motion, Account info, Payment info, Contact info, Device setup info, Device tech info, Device usage info

Privacy policy: www.NS200.smartdeviceco.com/policy

More Information

Detailed Security & Privacy Label:
www.iotsecurityprivacy.org/featured/external/manufacturer/Smart/Video-Doorbell

CMU IoT Security and Privacy Label **CISPL 1.0** iotsecurityprivacy.org

PUBLIC DOMAIN

Sources: White House, Carnegie Mellon University

EU Digital Product Passport for Digital Traceability

Considerations for Data Policies Across Value Chains

1	Product Groups	Product by Product	Industry by Industry			
2	Company Size	All Sizes	Large First	Large Only		
3	Application Level	Item	Batch	Product Model		
4	Data Storage	EU Federated	Company	Centralized	Decentralized	
5	Data Carrier **IDs**	**Root of Trust**	**QR Code**	**Barcode**	**RFID**	**NFC**	**Marker**
6	Access Security	Full	Minimum	Differentiated		
7	Requirements	Standardization	Product Spec	Combination		
8	Governance	No Assurance	Limited	Reasonable		

Sources: The EU Digital Passport WBCSD-BCG, Catena-X Automotive, Gaia-X Platform

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2024 - IoTAB Adopting Traceability Across Borders

Journey of chips through untrusted environments assembled with other chips into electronics and IoT products

1. **China** Rare Earth Metals
2. **S. Korea** Flash Memory
3. **Germany** Accelerometer
4. **Netherlands** NFC Controller
5. **Japan** Camera, LCD Screen
6. **USA** Wi-Fi & Audio Chips
7. **Taiwan** CPU/GPU Manufacturing
8. **China** Final Assembly & Test

Source: WBCSD and BCG



Digital Product Passport can have global impact as regulation applied to imported electronics and IoT parts will inspire cross border collaboration

U.S. Cyber Trust Mark will empower businesses, governments, and users to make informed decisions about IoT device security, privacy, etc.

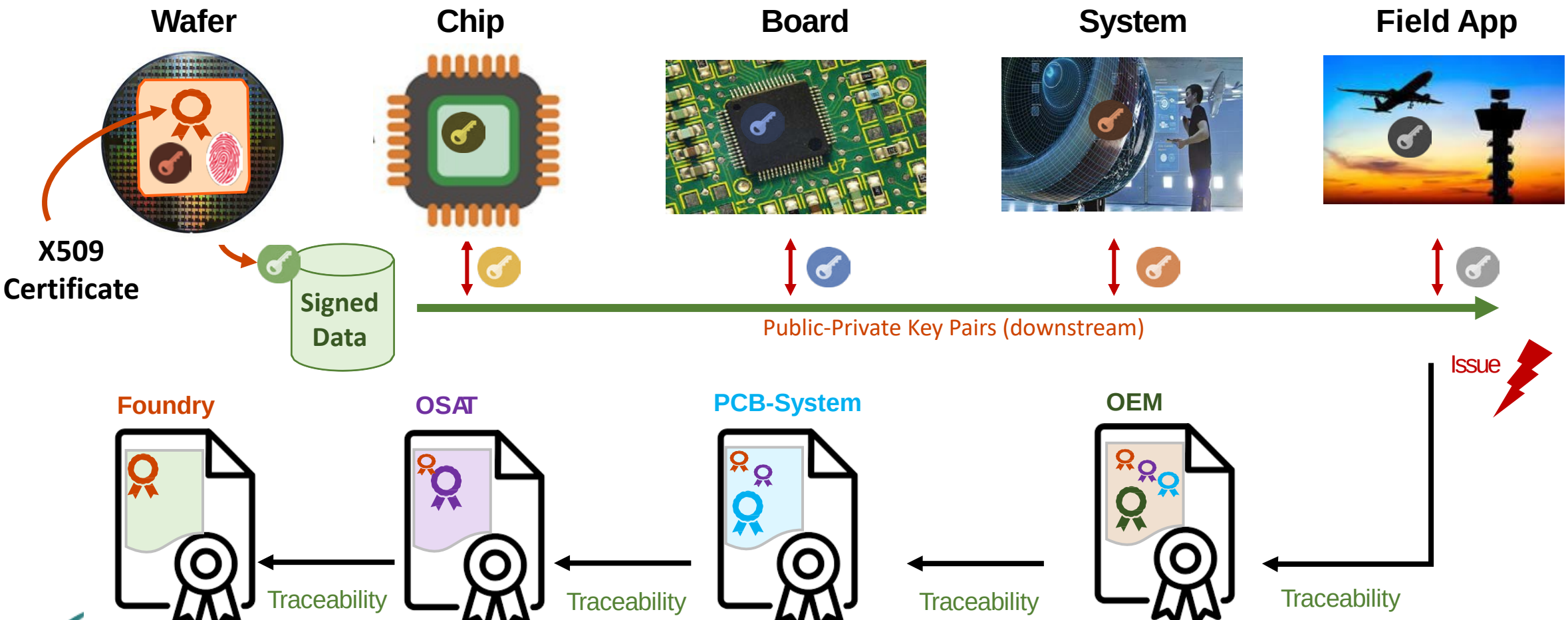
Global interoperability and identifier standards will enable trusted practices* for supply chain transparency, traceability and monetization

*Source - U.S. Customs and Border Protection [CBP Launches Global Business Identifier Pilot to Increase Supply Chain Visibility]

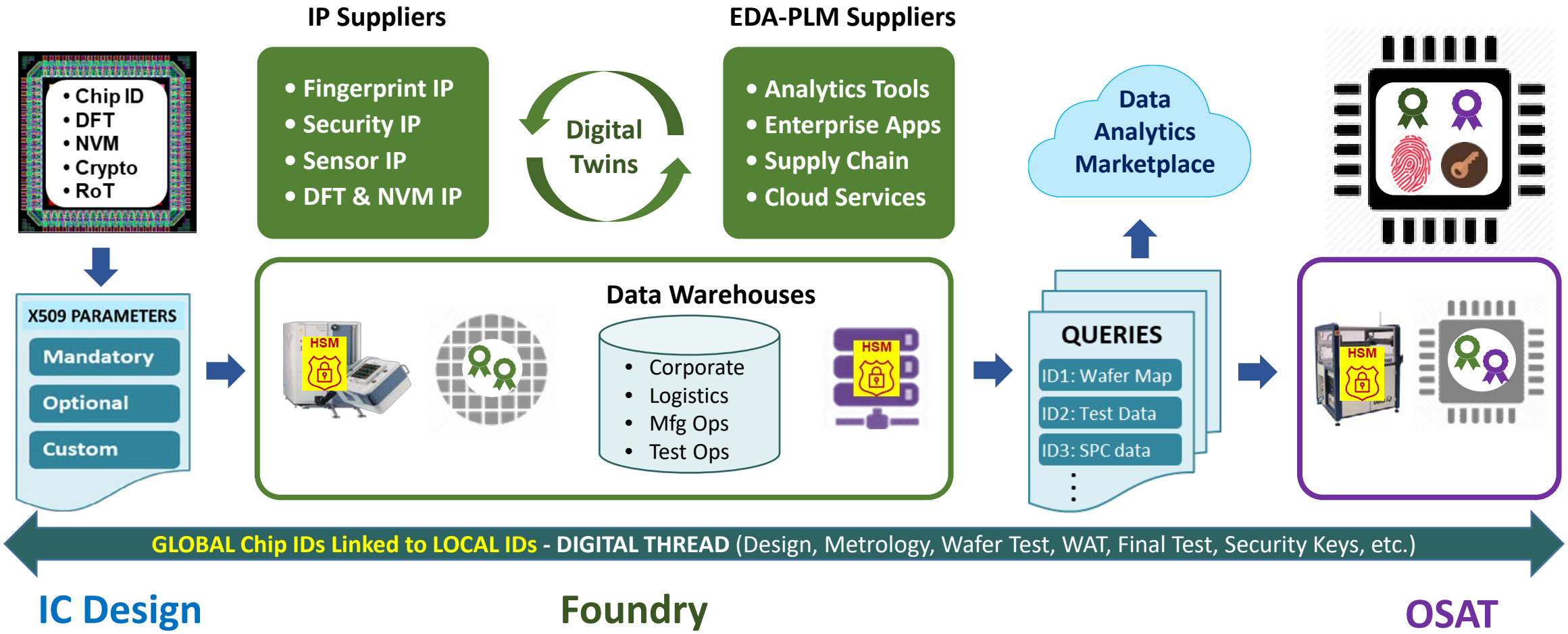
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2024 - Foundry Certificate Authority Project

Breakthrough *– Certificates Are Essential for Upstream & Downstream Traceability*



2024 - Foundry CA Collaborative Ecosystem Strategy



Multi-stakeholder business collaboration can establish origin(s) for chip provenance

Digital Thread Enables Data-AI Driven Monetization



Source: McKinsey & Company - 2017 Reimagining Fabs Advanced Analytics in Semiconductor Manufacturing 2021 Applying AI at Scale in Semiconductor Manufacturing

Traceable Value Chain	Data Producers	Data Consumers	Monetization
Electronics Design Simulation	EDA tools generate data from circuit design, optimization and performance.	Hardware designers, and device makers can use this data to improve products	Offer data-driven insights and add-on solutions to design and simulation tools.
Semiconductor Manufacturing	Produce vast amounts of data on quality, reliability, performance, integrity, etc.	Chip or equipment suppliers and device makers use data to improve products	Fabs license data to chip consumers to improve time-to-market & differentiation
Supply Chain Procurement	Create data for shipping, inventory levels, demand forecasting, availability, etc.	Manufacturers, logistics companies, retailers can increase forecast accuracy	Offer data access for customers to reduce, costs, and improve customer service.
IoT Device Deployment	Generate data related to device operation, sensors, user interactions, environment.	Businesses, insurance companies, and researchers use data to offer solutions.	OEMs get insights on field use, causes for bugs, RMAs, and predictive maintenance
Electronic Part Lifecyle	Generate data on specifications, quality availability, and lifecycle management	Chip and Device makers, repair services, parts, ESG and recycling organizations	Recycling data can be licensed to designers, suppliers, and eco-friendly organizations

Collaborative digital marketplaces enable Everything-as-a-service (XaaS*) revenue streams

*Source: Deloitte - How Semiconductor Companies can leverage XaaS to drive value creation Empower Your Customers with Hardware-as-a-Service

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2024 - STAMP US-EU Initiative for Traceability*



Semiconductor Ecosystem | **Electronics Ecosystem** | **IoT Ecosystem** | ***Cross Border***

Business Economics

Trusted Fab ROI | Power & Speed | Actual Value/Cost | Connectivity SLAs | **XaaS Platforms** | **Circular Economy**

U.S. Cyber Trust Mark

Digital Marketplaces

Trusted Digital Twins ***Trusted Data Analytics***

Asset Tracking

Chip Design & Mfg | **Packaging & Test** | **Embedded System** | **Vertical Markets** | **Edge Applications** | **Environments**

Public Private Partnerships

Chip ID

QR | RFID | Beacons

Trusted Digital Thread ***Trusted Digital Transformation***

EU Digital Passport

Secure-Trusted Infrastructure

Trustworthiness | Cybersecurity | Market Access | Confidentiality | Secure Onboard | Interoperability

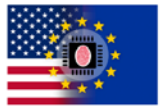
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***Source**: Department of Commerce appointed IoT Advisory Board report (Page 35)

2024 – STAMP Private Citizen Initiative

Objectives

Global Chip ID



- **Establish market preference for sovereign and assured chip supply**
  - Including a cross-border ability to regulate market access and use
- **Enhance supply chain logistics and visibility for global trade of chips**
  - Including supply-demand tracking, accountability, and transparency*
- **Enable secure & trusted chip production and lifecycle management**
  - Including monitoring field use, secure updates, recycling and end-of-life

https://ww

5/27/2025

Desired Outcomes

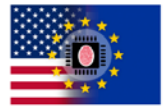


- **Start Public Private Partnerships** from chip design and manufacturing
  - Prove the value of digital twins, traceable chip supply, and Hardware-as-a-Service (HaaS)
  - Leverage analytics and AI to showcase how traceability can drive digital marketplaces
  - Expand orchestration and collaboration across the value chain to create market pull
- **Promote trusted digital marketplaces** across supply chains for chips and data
  - Leverage the **U.S. Cyber Trust Mark** (CTM or similar regional standard)
  - Link the **EU Digital Product Passport** (DPP or similar regional standard)
  - Link Business IDs and Customs & Border Protection* (CBP for cross border traceability)
- **Encourage multi-stakeholder initiatives**. No one enterprise can do it alone

https://www.cbp.gov/newsroom/national-media-release/cbp-launches-global-business-identifier-pilot-increase-supply-chain

5/27/2025 commercial in confidence 3

Goal of Initiative



- **Traceability of electronic components is beneficial to all stakeholders**
  - Safeguard allied nation markets from being flooded by adversaries' legacy chips
  - Strengthen export control and prevent western chips weaponized against our allies
  - Increase supply chain resilience and trust across enterprises in electronics value chains
  - Drive new business models (analytics marketplaces, HaaS, IoT and AI applications)
  - Create workforces across chip supply chains and protect critical infrastructure
- **Global unique identification for tracing chips is urgent and essential**
  - Current practices are inadequate (local traceability, varied mechanisms)
- **This initiative aims to align allied nations on a "Global Chip Identifier"**
  - Identifier can link to Businesses, Assets, and related Data for chips and electronics
  - Follows best practices in other industries and supply chains

5/27/2025 4

References to IoTAB Report

Need for Global Digital Identifiers (Page 61)

Incentivizing Global Digital IDs (Page 84)

Global Digital ID Recommendation (Page 92)

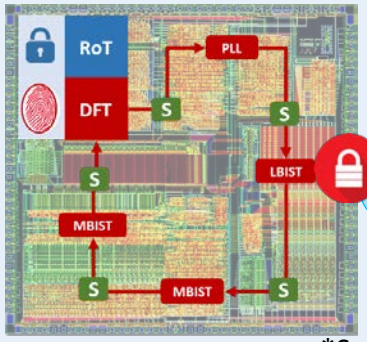
Bloomberg Article - Exploding Pagers Raise Global Supply-Chain Security Concern

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2024 – STAMP Business Use Cases (Shift Left)



Automotive - Silicon Lifecycle Management (SLM)



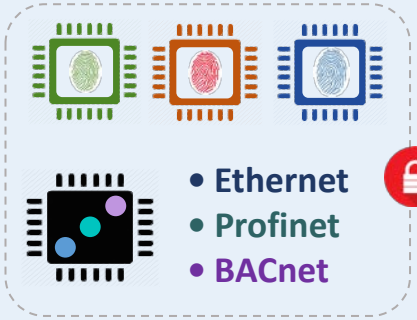
Functional Safety

Fleet Monitoring



*Source: Semiconductor Eng

Industrial - Chip Licensing & Multi Market Product XaaS



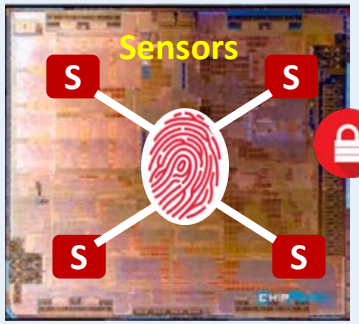
HW + SW Provisioning



*Sources: Intel - Pay-as-you-go Chip Licensing, Samsung - Memory Chip Rental Service

Global Chip ID

Aerospace & Defense - Manufacturing Integrity

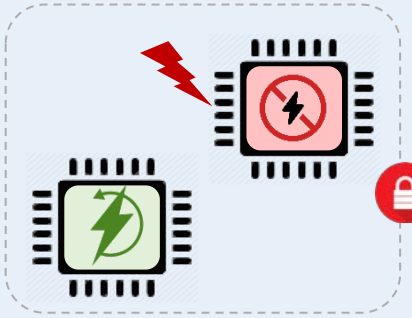


Failure Prevention



Source: ERI Summit 2020

Supply Chain - Monitoring & Regulating Field Use



Disable Adversary



Sources: Reuters - Western chips in Russian drones, WSJ - Cheap drones in battlefields

***Source**: STAMP European Workshop November 19, 2024

March 2025 – STAMP Traceability Dimensions Leading to ORG



Workshop Agenda

10:00-10:15 AM – **Welcome & Workshop Overview**
Introduction by Dan DiMase, Jim Gobes, Rick McCormick
Key organizational goals & expected outcomes

10:15-10:45 AM – **Keynote: The Need and Vision for the Future**
Speaker: Jeremy Muldavin
Addressing security challenges in semiconductor supply chains

10:45-11:30 AM – **European Progress and Coordination**
Speakers: Eduard Hoeberichts, Patrick Langlois , Johanna Baehr
Update on Global Chip Traceability initiative Workshop in the EU, Feasibility Study, and Fraunhofer AISEC WG on Velektronik Trusted Microelectronics

11:30 AM-12:15 PM – **Architectural Solutions & Panel Discussion**
Moderator: Don Davidson
Panelists:
- *UT Dallas - Yiorgos Makris,*
- *University of Kansas - Sumaiya Shomaji*
- *Hushmesh - Manu Fontaine*
- *Micron - Jeff Shiner*

Panelists from industry and government discussing architectural approaches and solutions

12:30-1:30 PM – **Standards Panel**
Moderator: Dan DiMase
Panelists:
- *SEMI – Paul Trio: Director, Standards*
- *SAE – Rich King: Director, Government & Industry Affairs, Aerospace*
- *IPC/USPAE – James Will: Executive Director*
- *NIST – Sanjay Rekhi: Group Leader of the Security Components and Mechanisms Group within the Computer Security Division*
- *Ford Motor Co - Gloria D'Anna – SAE G-32 Co-Chair*

1:30-2:30 PM – **Traceability Economics and Business Models**
Moderator: Tom Katsioulas
- *Airbus - Andreas Schweiger: System Architect, Defense & Space*
- *Lockheed Martin - Brian Gabriel: Critical Materials Senior Manager*
- *Infineon - Theodore Varelas: Director Strategic Initiatives, Digital Security & Identity*
- *GlobalFoundries - Ezra Hall: GF Worldwide A&D Business leader*
- *Integra Technologies - Sultan Lilani: Technical Business Development*
- *Cadence Design Systems - Steve Carlson: Technology and Market Strategist*
- *Tartan Silicon Inc. - Alan Aronoff: Founder and CEO*
- *Synopsys - Reed Hinkel: Director, Strategic Programs*
- *PDF Solutions - Christophe Begue: Vice President of Corporate Strategic Marketing*

Driving value from end applications to chip design and manufacturing

2:30-3:00 PM – **Meta-framework for Supply Chain Trustability**
Speaker: Micheal Pease
Update on NIST IR8536 efforts and the meta-framework

- Need and Vision for the Future
- European Coordination (Cross Border)
- Architectural & Platform Solutions
- Existing Standards and Harmonization
- Economics and Business Models
- Meta Framework Distributed Chaining
- Ecosystem Initiative Study and Pilot

***Source**: STAMP U.S. Workshop March 4, 2025

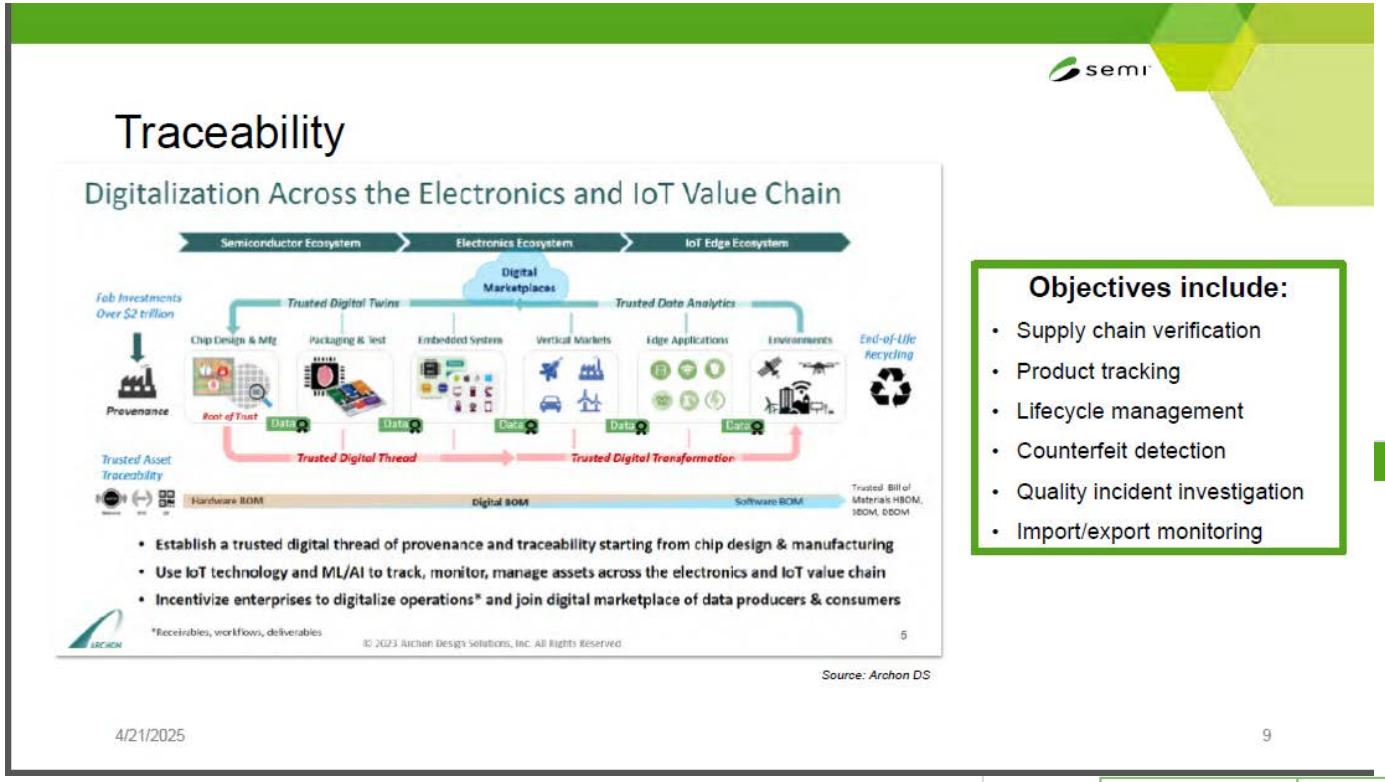
April 2025 – NIST Traceability Workshop

Agenda Item	Who
1. Welcome and Workshop Briefing	James St Pierre (NIST)
2. Overview of the Meeting Objectives and Desired Outcomes	Sanjay Rekhi (NIST) Kostas Amberiadis (NIST)
3. Trust and Provenance Challenges in the Semiconductor Supply Chain	Alex Tzonkov (AMD) Dan O'Loughlin (Qualcomm) Shawn Fetterolf (Intel)
4. Solution Exploration: Possible Approaches and Technologies	Scott Best (Rambus) Eric Sivertson (Lattice) David Sequino (ISS) Jeremy Muldavin (Cadence)
6. Standards and Requirements	Paul Trio (SEMI)
7. Supply Chain Traceability	Michael J. Pease (NIST)
8. FY23 NDAA Section 5949	Rebecca McWhite (NIST)
9. Breakout Sessions	Kostas Amberiadis (NIST) Matt Areno (Rickert-A Eng.) Ankur Srivastava (UMD)
10. Summarize Breakout Sessions	Session Leaders
11. Next Steps: Roadmap for Implementation and Collaboration	Sanjay Rekhi (NIST) Kostas Amberiadis (NIST)
12. Closing Remarks and Adjournment	Matthew Scholl (NIST) Sanjay Rekhi (NIST) Kostas Amberiadis (NIST)

***Source**: NIST Workshop, April 15, 2025

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2025 – SEMI Phase-0 Traceability Initiative

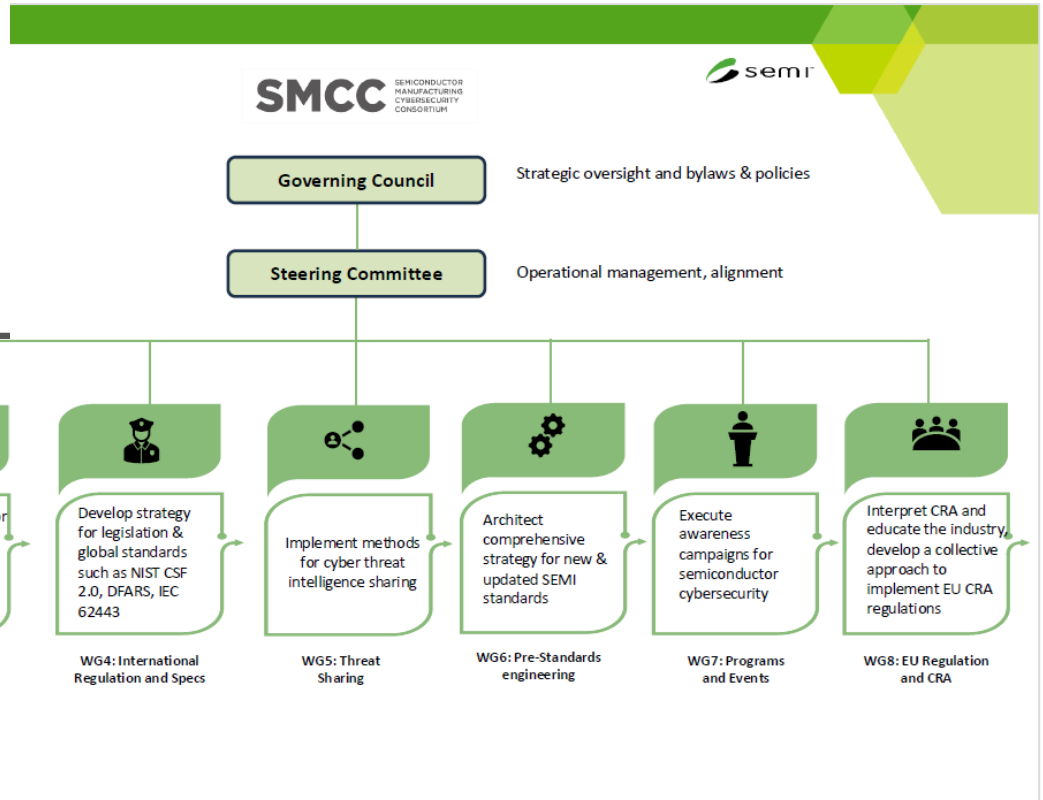


Objectives include:

- Supply chain verification
- Product tracking
- Lifecycle management
- Counterfeit detection
- Quality incident investigation
- Import/export monitoring

SEMI Traceability Standards

T25, T23, T22, T21, T20, T18, T17, T13, T12, 7234, 7301



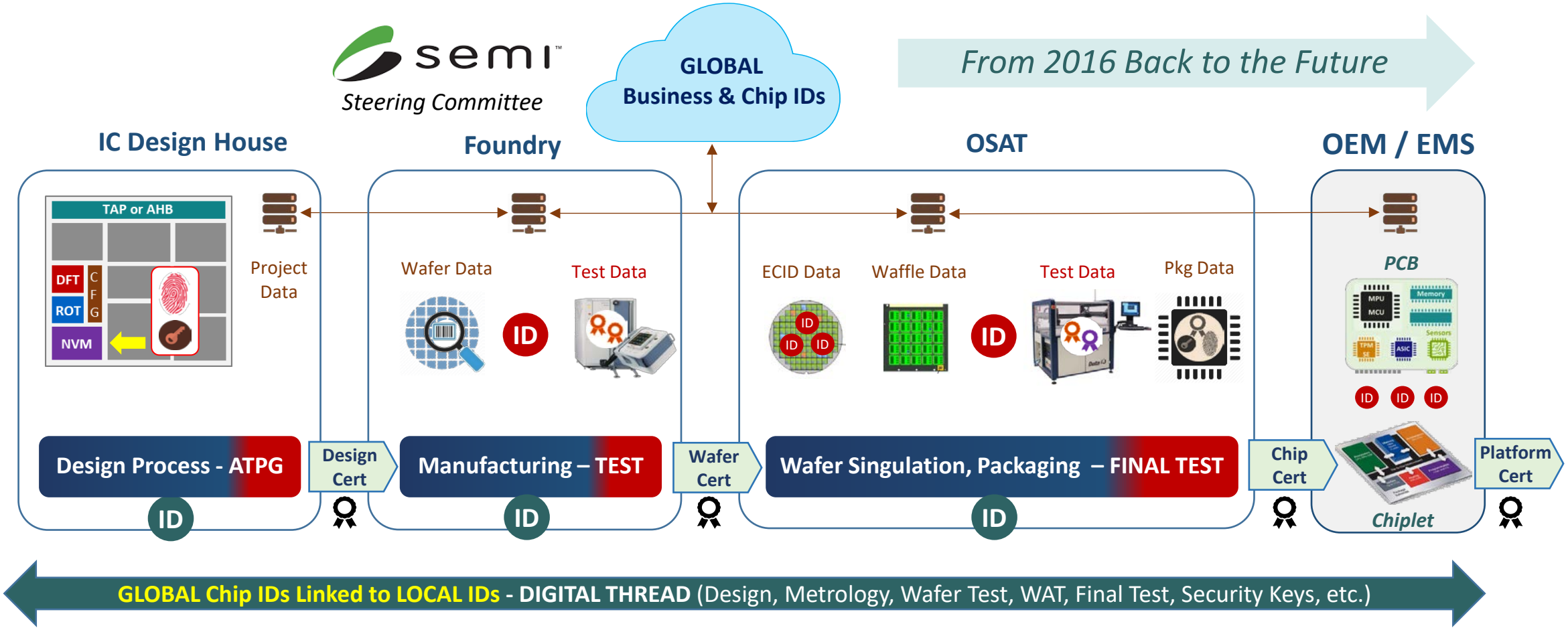
***Source**: NIST Workshop, April 15, 2025

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2026 – Need for Pilot Project to Show Potential Value

Small Scope Collaboration for Provenance *- EDA/IP, Fabless IC, Foundry, CA, OSAT → Hyperscalers, PLM, OEM, EMS*



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2026 - Momentum Toward Global Traceability Alliance

Supported by Legislation U.S. NDAA §5949, EU Cyber Resilience Act, U.S. Chip Security Act

Industry, Government, ORGs, Academia



	Current Initiatives	Future Direction
Purpose	Implementation Platform	Promotional Platform
Foundation	Supply Chain Applications	Supply Chain Infrastructure
Context	Multi-stakeholder Operational	Ecosystem Operational
Scope	Small Scope Pilot Partnership	Broad Stakeholder Community
Focus	Cross Border Monetization	Multi-sector Collaboration
Partnerships	Fabless IC, EDA/IP, Foundries, OSATs, and CA Vendors	End Market-Driven, OEMs, PLM, Cloud, SDOs, Policymakers
Output	Business Use Case Validation	Use Case Knowledge base

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